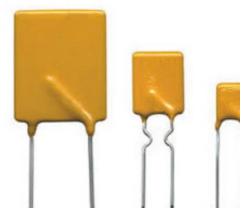


## Features

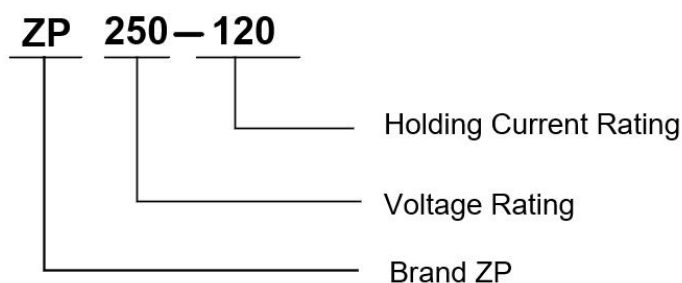
- ◆ Radial leaded devices.
- ◆ Over-current protection
- ◆ High voltage surge capabilities
- ◆ Flame retardant epoxy polymer insulating material meets UL94 V-0 requirement
- ◆ Available in lead-free version.
- ◆ Meets MSL level 1, per J-STD-020
- ◆ Operating Temperature: -40°C~+85°C



## Applications

- ◆ USB hubs, ports and periphera
- ◆ IT equipment
- ◆ Access network equipment
- ◆ Central office equipment
- ◆ ISDN and xDSL equipments
- ◆ Phone set and fax machine
- ◆ LAN/WAN and VOIP cards

## Part Number Code and Making



## Dimensions (unit:mm)

Symbol	Dimension	
	Millimeters	
	Min.	Max.
A	--	6.5
B	--	10.5
C	4.6	5.6
D	--	4.6
Lead	0.6	

Electrical Characteristics ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Part Number	$I_H$ (A)	$I_T$ (A)	$U_{Max}$ (V)	$I_{Max}$ (A)	$P_{DTYP}$ (W)	Time-To-trip		$R_{Min}$ ( $\Omega$ )	$R_{Max}$ ( $\Omega$ )	$R_{1Max}$ ( $\Omega$ )
						$I_{Trip}(A)$	$T_{Max}(S)$			
ZP250-120	0.12	0.24	265	1.2	1.0	0.36	15	6	12	16

$I_H$  = Hold current: maximum current device will pass without tripping in  $25^{\circ}\text{C}$  still air.

$I_T$  = Trip current minimum current at which the device will trip in  $25^{\circ}\text{C}$  still air.

$U_{Max}$  = Maximum voltage device can withstand without damage at rated current ( $I_{max}$ ).

$I_{max}$  = Maximum fault current device can withstand without damage at rated voltage ( $V_{max}$ ).

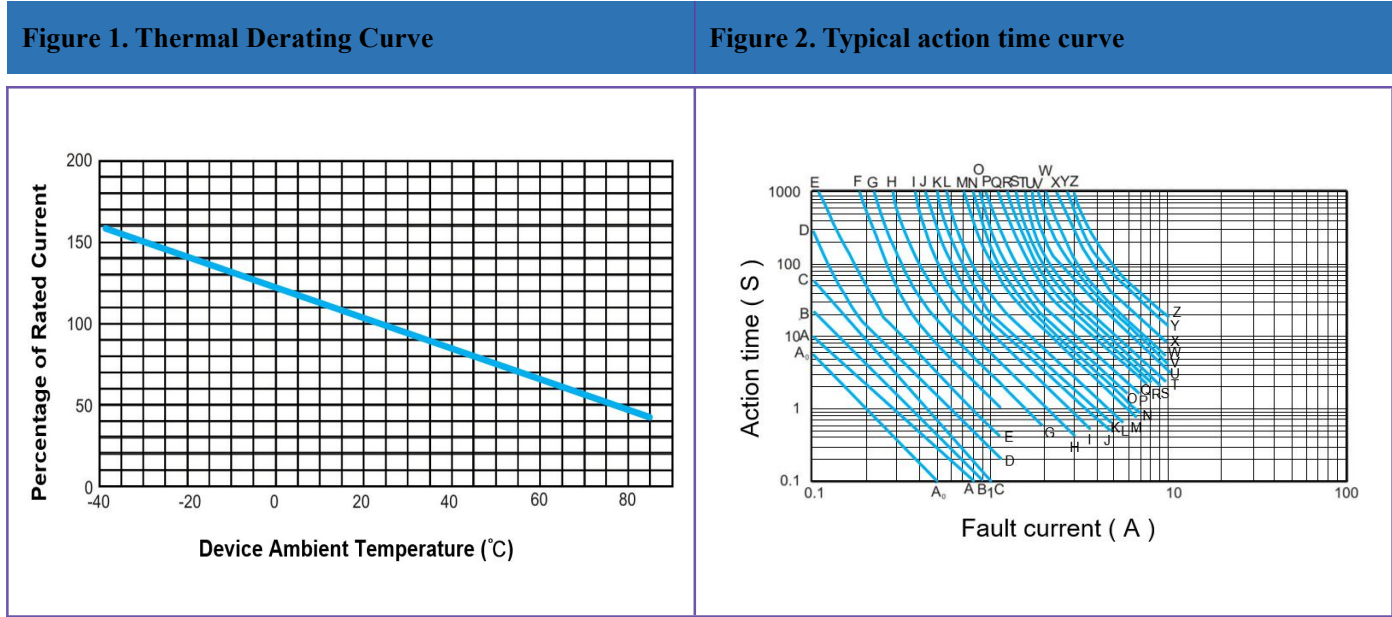
$P_{DTYP}$  = Typical Power dissipated from device when in the tipped state at  $25^{\circ}\text{C}$  still air.

$R_{min}$  = Minimum resistance of device in initial(un-soldered) state.

$R_{Max}$  =Maximum resistance of device in initial (un-soldered) state.

$R_{1max}$  = Maximum resistance of device at  $25^{\circ}\text{C}$  measured one hour after tripping or reflow soldering of  $260^{\circ}\text{C}$  for 20 sec.

Ratings and Characteristic Curves (TA=25°C unless otherwise noted)



Part Number	Ambient Operation Temperature								
	-40℃	-20℃	0℃	25℃	40℃	50℃	60℃	70℃	85℃
ZP250-120	0.186	0.164	0.143	0.120	0.098	0.088	0.077	0.066	0.049

Wave Soldering Parameters

